

06/12/01

Class	Subcl	ISSUE CLASSIFICA
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U.S. **UTILITY** Patent Application

<p><u>IR</u></p> <p>SCANNED <u>KC3</u> G.A. <u>SM</u></p>	<p>O.I.P.E.</p> <p>PATENT DATE</p>
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APPLICATION NO. 09/881514	CONT/PRIOR D	CLASS 216	SUBCLASS 38	ART UNIT 1746 1163	EXAMINER Ahmed
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APPLICANTS

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Michael Lee
William Chow
Larry Moresco

P6 Pubs
DONE

TITLE

Methods of planarizing structures on wafers and substrates by polishing

PTO-2040
12/89

ISSUING CLASSIFICATION												
ORIGINAL					CROSS REFERENCE(S)							
CLASS		SUBCLASS			CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)						
INTERNATIONAL CLASSIFICATION												

☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) _____ (Date)			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____ _____ _____				ISSUE FEE	
	_____ (Primary Examiner) _____ (Date)	Amount Due	Date Paid		
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			ISSUE BATCH NUMBER	
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